

2SB0835 (2SB835)

Silicon PNP epitaxial planer type

For low-frequency output amplification

Features

- Low collector to emitter saturation voltage $V_{CE(sat)}$.
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	-20	V
Collector to emitter voltage	V_{CEO}	-18	V
Emitter to base voltage	V_{EBO}	-5	V
Peak collector current	I_{CP}	-2	A
Collector current	I_C	-1	A
Collector power dissipation	P_C^*	1	W
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 ~ +150	°C

* Printed circuit board: Copper foil area of 1cm² or more, and the board thickness of 1.7mm for the collector portion

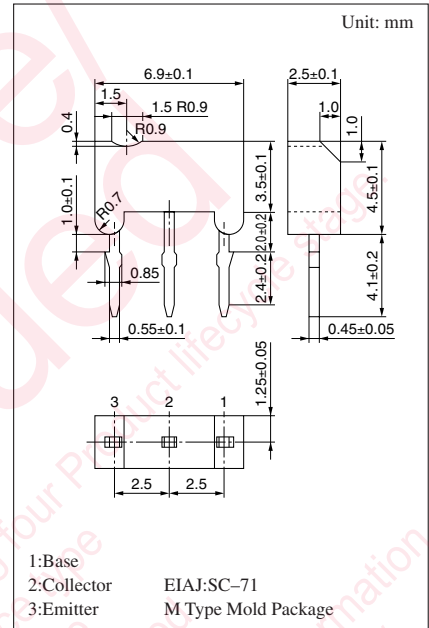
Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = -10V, I_E = 0$			-1	μA
	I_{CEO}	$V_{CE} = -18V, I_B = 0$			-10	μA
Collector to base voltage	V_{CBO}	$I_C = -10\mu A, I_E = 0$	-20			V
Collector to emitter voltage	V_{CEO}	$I_C = -1mA, I_B = 0$	-18			V
Emitter to base voltage	V_{EBO}	$I_E = -10\mu A, I_C = 0$	-5			V
Forward current transfer ratio	h_{FE1}^*	$V_{CE} = -2V, I_C = -0.5A$	130		280	
	h_{FE2}	$V_{CE} = -2V, I_C = -1.5A$	50			
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -1A, I_B = -50mA$			-0.5	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = -500mA, I_B = -50mA$			-1.2	V
Transition frequency	f_T	$V_{CB} = -6V, I_E = 50mA, f = 200MHz$		200		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -6V, I_E = 0, f = 1MHz$		40		pF

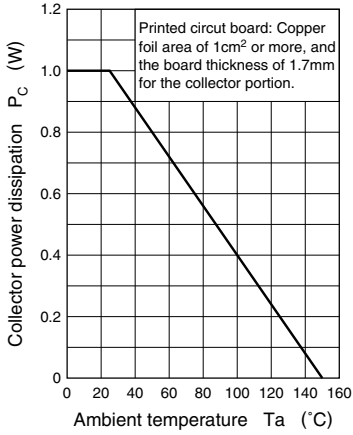
* h_{FE1} Rank classification

Rank	R	S
h_{FE1}	130 ~ 210	180 ~ 280

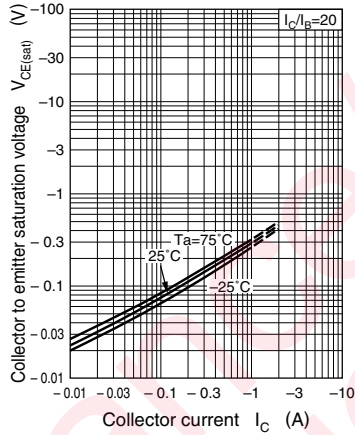
Note.) The Part number in the Parenthesis shows conventional part number.



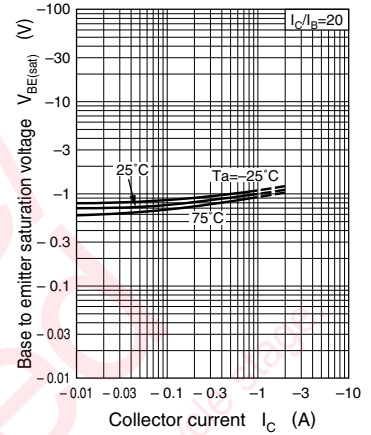
$P_C - T_a$



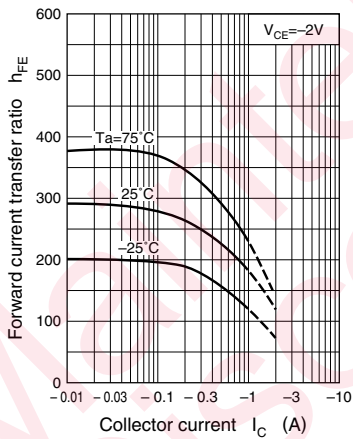
$V_{CE(sat)} - I_C$



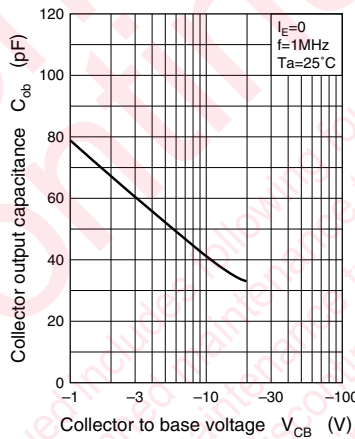
$V_{BE(sat)} - I_C$



$h_{FE} - I_C$



$C_{ob} - V_{CB}$



2SB
Type

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